



Material Content Data Sheet



Halogen-Free

Sales Product Name	2ED2109S06F	Issued	14. May 2021
MA#	MA002704374		
Package	PG-DSO-8-70	Weight*	75.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.437	1.91	1.91	19101	19101
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.031	0.04		418	
	non noble metal	iron	7439-89-6	0.628	0.84		8351	
	non noble metal	copper	7440-50-8	25.502	33.91	34.80	339092	347965
wires	noble metal	palladium	7440-05-3	0.000			6	
	non noble metal	copper	7440-50-8	0.045	0.06	0.06	604	610
encapsulation	organic material	carbon black	1333-86-4	0.230	0.31		3052	
	plastics	epoxy resin	-	6.198	8.24		82417	
	inorganic material	silicondioxide	60676-86-0	39.486	52.49	61.04	525024	610493
leadfinish	non noble metal	tin	7440-31-5	0.833	1.11	1.11	11081	11081
plating	noble metal	silver	7440-22-4	0.134	0.18	0.18	1776	1776
glue	plastics	acrylic resin	-	0.148	0.20		1974	
	noble metal	silver	7440-22-4	0.526	0.70	0.90	7000	8974
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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